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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	72
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	5.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2la8aanfp-v0

1.1.2 Differences between Groups

Table 1.1 lists the Differences between Groups, Tables 1.2 and 1.3 list the Programmable I/O Ports Provided for Each Group, and Tables 1.4 and 1.5 list the LCD Display Function Pins Provided for Each Group.

Figures 1.9 to 1.12 show the pin assignment for each group, and Tables 1.9 to 1.12 list product information.

The explanations in the chapters which follow apply to the R8C/LA8A Group only. Note the differences shown below.

Table 1.1 Differences between Groups

Item	Function	R8C/LA3A Group	R8C/LA5A Group	R8C/LA6A Group	R8C/LA8A Group
I/O Ports	Programmable I/O ports	26 pins	44 pins	56 pins	72 pins
	High current drive ports	8 pins	8 pins	8 pins	10 pins
Interrupts	$\overline{\text{INT}}$ interrupt pins	5 pins	6 pins	8 pins	8 pins
Timer RJ	Timer RJ0 output pin	None	None	None	1 pin
	Timer RJ1 output pin	None	None	None	1 pin
	Timer RJ2 I/O pin	None	None	None	1 pin
	Timer RJ2 output pin	None	None	None	1 pin
Timer RH	Timer RH output pin	None	1 pin	1 pin	1 pin
Serial interface	UART2	None	None	1 pin	1 pin
A/D Converter	Analog input pins	5 pins	7 pins	8 pins	12 pins
LCD Drive Control Circuit	Segment output pins	Max. 11 pins	Max. 27 pins	Max. 32 pins	Max. 40 pins
Comparator B	Analog input voltage	1 pin	2 pins	2 pins	2 pins
	Reference input voltage	1 pin	2 pins	2 pins	2 pins
Clock	XCIN pin	Shared with XIN pin	Dedicated pin	Dedicated pin	Dedicated pin
	XCOUT pin	Shared with XOUT pin	Dedicated pin	Dedicated pin	Dedicated pin
Packages		32-pin LQFP	52-pin LQFP	64-pin LQFP	80-pin LQFP

Note:

1. I/O ports are shared with I/O functions, such as interrupts or timers.
Refer to Tables 1.13 to 1.17, Pin Name Information by Pin Number, for details.

1.2 Product Lists

Tables 1.9 to 1.12 list product information for each group. Figures 1.1 to 1.4 show the Correspondence of Part No., with Memory Size and Package for each group.

Table 1.9 Product List for R8C/LA3A Group

Current of Oct 2011

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2LA32ANFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	N Version
R5F2LA34ANFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	
R5F2LA36ANFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	
R5F2LA38ANFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0032GB-A	
R5F2LA32ADFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	D Version
R5F2LA34ADFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	
R5F2LA36ADFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0032GB-A	
R5F2LA38ADFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0032GB-A	

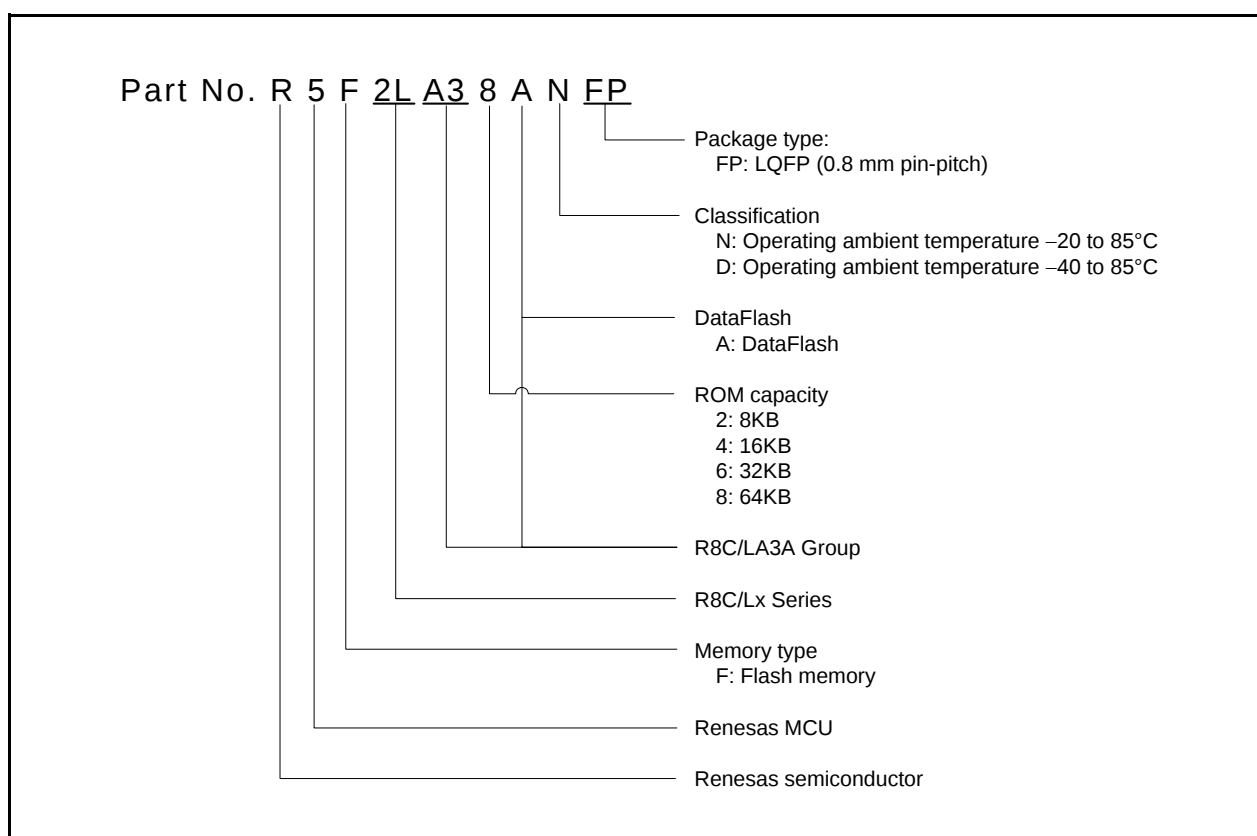


Figure 1.1 Correspondence of Part No., with Memory Size and Package of R8C/LA3A Group

Table 1.10 Product List for R8C/LA5A Group**Current of Oct 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2LA52ANFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	N Version
R5F2LA54ANFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA56ANFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA58ANFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0052JA-A	
R5F2LA52ADFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	D Version
R5F2LA54ADFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA56ADFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA58ADFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0052JA-A	

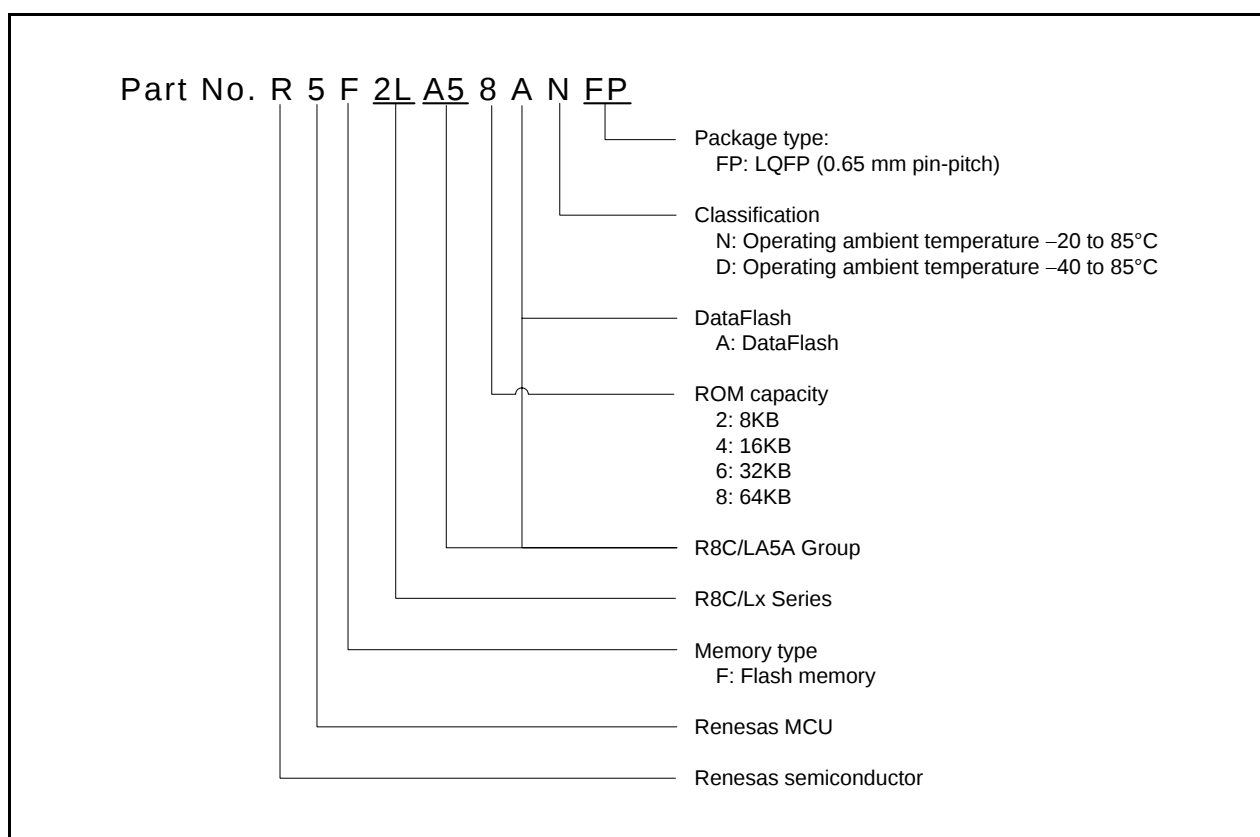
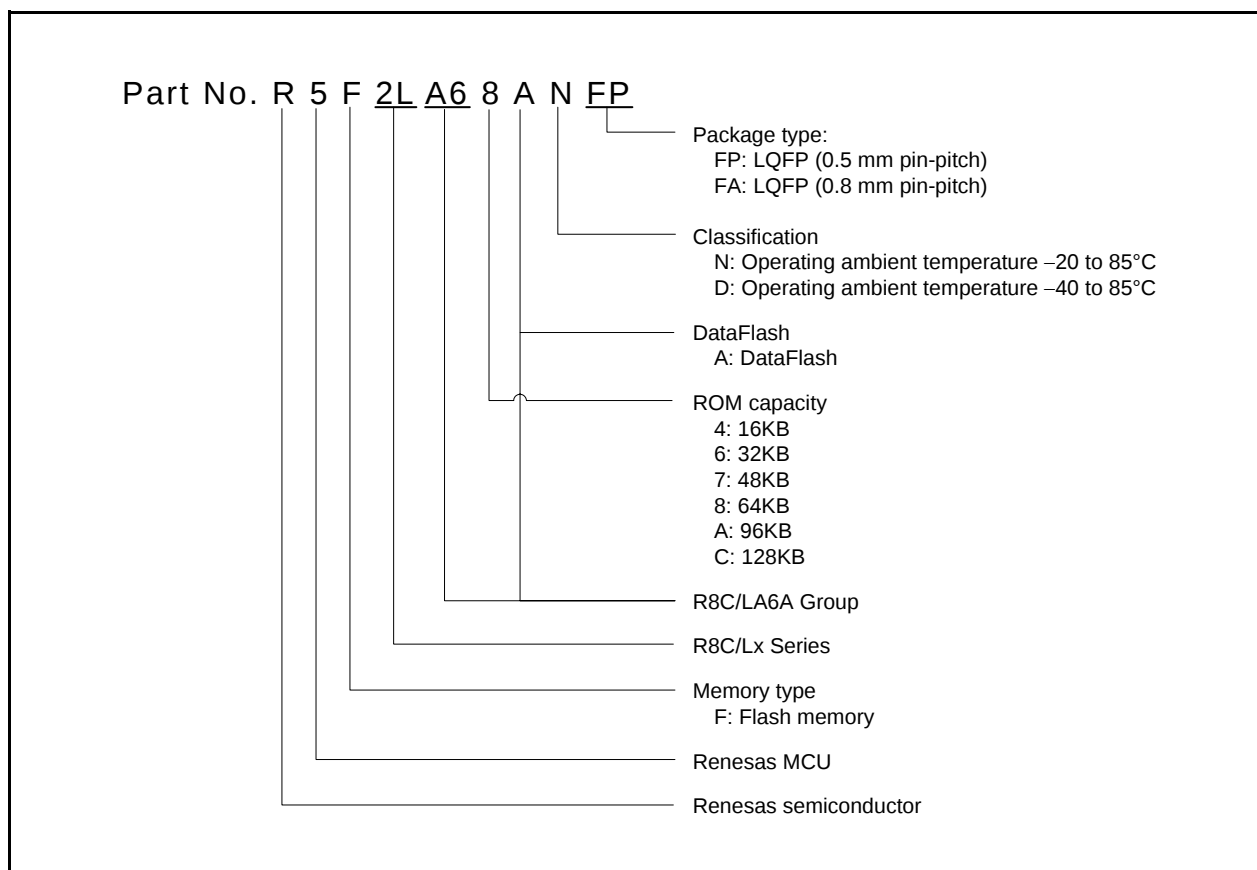
**Figure 1.2 Correspondence of Part No., with Memory Size and Package of R8C/LA5A Group**

Table 1.11 Product List for R8C/LA6A Group**Current of Oct 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2LA64ANFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064KB-A	N Version
R5F2LA64ANFA	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064GA-A	
R5F2LA66ANFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064KB-A	
R5F2LA66ANFA	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064GA-A	
R5F2LA67ANFP	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064KB-A	
R5F2LA67ANFA	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064GA-A	
R5F2LA68ANFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064KB-A	
R5F2LA68ANFA	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064GA-A	
R5F2LA6AANFP	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064KB-A	
R5F2LA6AANFA	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064GA-A	
R5F2LA6CANFP	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064KB-A	
R5F2LA6CANFA	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064GA-A	
R5F2LA64ADFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064KB-A	D Version
R5F2LA64ADFA	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064GA-A	
R5F2LA66ADFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064KB-A	
R5F2LA66ADFA	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0064GA-A	
R5F2LA67ADFP	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064KB-A	
R5F2LA67ADFA	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064GA-A	
R5F2LA68ADFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064KB-A	
R5F2LA68ADFA	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0064GA-A	
R5F2LA6AADFP	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064KB-A	
R5F2LA6AADFA	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064GA-A	
R5F2LA6CADFP	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064KB-A	
R5F2LA6CADFA	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0064GA-A	

**Figure 1.3 Correspondence of Part No., with Memory Size and Package of R8C/LA6A Group**

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

Table 4.13 SFR Information for R8C/LA8A Group (4) ⁽¹⁾

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh	A/D Control Register 2	ADCON2	00h
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh	Port P7 Register	P7	XXh
00EEh	Port P6 Direction Register	PD6	00h
00EFh	Port P7 Direction Register	PD7	00h
00F0h	Port P8 Register	P8	XXh
00F1h	Port P9 Register	P9	XXh
00F2h	Port P8 Direction Register	PD8	00h
00F3h	Port P9 Direction Register	PD9	00h
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

- Blank spaces are reserved. No access is allowed.

5. Electrical Characteristics

5.1 Electrical Characteristics (R8C/LA3A Group and R8C/LA5A Group)

5.1.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V _{cc} /AV _{cc}	Supply voltage			−0.3 to 6.5	V
V _i	Input voltage	XIN	XIN-XOUT oscillation on (oscillation buffer ON) ⁽¹⁾	−0.3 to 1.9	V
		XIN	XIN-XOUT oscillation on (oscillation buffer OFF) ⁽¹⁾	−0.3 to V _{cc} + 0.3	V
		P5_4/VL1		−0.3 to VL2 ⁽²⁾	V
		P5_5/VL2		VL1 to VL3	V
		P5_6/VL3		VL2 to 6.5	V
		Other pins		−0.3 to V _{cc} + 0.3	V
V _o	Output voltage	XOUT	XIN-XOUT oscillation on (oscillation buffer ON) ⁽¹⁾	−0.3 to 1.9	V
		XOUT	XIN-XOUT oscillation on (oscillation buffer OFF) ⁽¹⁾	−0.3 to V _{cc} + 0.3	V
		COM0 to COM3		−0.3 to VL3	V
		SEG0 to SEG26		−0.3 to VL3	V
		Other pins		−0.3 to V _{cc} + 0.3	V
P _d	Power dissipation		−40 °C ≤ T _{opr} ≤ 85 °C	500	mW
T _{opr}	Operating ambient temperature			−20 to 85 (N version)/ −40 to 85 (D version)	°C
T _{stg}	Storage temperature			−65 to 150	°C

Notes:

1. For the register settings for each operation, refer to **7. I/O Ports** and **9. Clock Generation Circuit** in the User's Manual: Hardware.
2. The VL1 voltage should be VCC or below.

5.1.2 Recommended Operating Conditions

Table 5.2 Recommended Operating Conditions
($V_{CC} = 1.8$ to 5.5 V and $T_{opr} = -20$ to 85 °C (N version)/ -40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage					1.8	—	5.5	V
V _{SS} /AV _{SS}	Supply voltage					—	0	—	V
V _{IH}	Input “H” voltage	Other than CMOS input			4.0 V ≤ V _{CC} ≤ 5.5 V	0.8 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.8 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.9 V _{CC}	—	V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.5 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.55 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.65 V _{CC}	—	V _{CC}	V
				Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.65 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.7 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.8 V _{CC}	—	V _{CC}	V
				Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.85 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.85 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.85 V _{CC}	—	V _{CC}	V
V _{IL}	Input “L” voltage	Other than CMOS input			4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.05 V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.2 V _{CC}	V
				Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.4 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.3 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.2 V _{CC}	V
				Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.55 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.45 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.35 V _{CC}	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)				—	—	−160	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)				—	—	−80	mA
I _{OH} (peak)	Peak output “H” current	Port P8 (2)				—	—	−40	mA
		Other pins				—	—	−10	mA
I _{OH} (avg)	Average output “H” current (1)	Port P8 (2)				—	—	−20	mA
		Other pins				—	—	−5	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)				—	—	160	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)				—	—	80	mA
I _{OL} (peak)	Peak output “L” current	Port P8 (2)				—	—	40	mA
		Other pins				—	—	10	mA
I _{OL} (avg)	Average output “L” current (1)	Port P8 (2)				—	—	20	mA
		Other pins				—	—	5	mA
f _(XIN)	XIN clock input oscillation frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	2	—	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	2	—	8	MHz
f _(XCIN)	XCIN oscillation frequency				1.8 V ≤ V _{CC} ≤ 5.5 V	—	32.768	—	kHz
	XCIN external clock input frequency				1.8 V ≤ V _{CC} ≤ 5.5 V	—	—	50	kHz
f _{OCO20M}	When used as the count source for timer RC (3)				2.7 V ≤ V _{CC} ≤ 5.5 V	18.432	—	20	MHz
f _{OCO-F}	fOCO-F frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	-	-	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	-	-	8	MHz
—	System clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	-	-	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	-	-	8	MHz
f _(BCLK)	CPU clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	0	-	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	0	-	8	MHz

Notes:

1. The average output current indicates the average value of current measured during 100 ms.
2. This applies when the drive capacity of the output transistor is set to High by P8DRR register. When the drive capacity is set to Low, the value of any other pin applies.
3. fOCO20M can be used as the count source for timer RC in the range of $V_{CC} = 2.7$ V to 5.5V.

Table 5.9 Voltage Detection 0 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Vdet0	Voltage detection level Vdet0_0 (1)			1.8	1.90	2.05	V
	Voltage detection level Vdet0_1 (1)			2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 (1)			2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (1)			3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (3)	In operation	At the falling of Vcc from 5 V to (Vdet0_0 – 0.1) V	—	50	500	μs
		In stop mode	At the falling of Vcc from 5 V to (Vdet0_0 – 0.1) V	—	100	500	μs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V		—	1.5	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts (2)			—	—	100	μs

Notes:

1. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
3. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.10 Voltage Detection 1 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Vdet1	Voltage detection level Vdet1_0 ⁽¹⁾	At the falling of Vcc		2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 ⁽¹⁾	At the falling of Vcc		2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 ⁽¹⁾	At the falling of Vcc		2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 ⁽¹⁾	At the falling of Vcc		2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 ⁽¹⁾	At the falling of Vcc		2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 ⁽¹⁾	At the falling of Vcc		2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 ⁽¹⁾	At the falling of Vcc		2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 ⁽¹⁾	At the falling of Vcc		3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 ⁽¹⁾	At the falling of Vcc		3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 ⁽¹⁾	At the falling of Vcc		3.30	3.55	3.85	V
	Voltage detection level Vdet1_A ⁽¹⁾	At the falling of Vcc		3.45	3.70	4.00	V
	Voltage detection level Vdet1_B ⁽¹⁾	At the falling of Vcc		3.60	3.85	4.15	V
	Voltage detection level Vdet1_C ⁽¹⁾	At the falling of Vcc		3.75	4.00	4.30	V
	Voltage detection level Vdet1_D ⁽¹⁾	At the falling of Vcc		3.90	4.15	4.45	V
	Voltage detection level Vdet1_E ⁽¹⁾	At the falling of Vcc		4.05	4.30	4.60	V
	Voltage detection level Vdet1_F ⁽¹⁾	At the falling of Vcc		4.20	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected		—	0.07	—	V
		Vdet1_6 to Vdet1_F selected		—	0.10	—	V
—	Voltage detection 1 circuit response time ⁽²⁾	In operation	At the falling of Vcc from 5 V to (Vdet1_0 – 0.1) V	—	60	150	μs
		In stop mode	At the falling of Vcc from 5 V to (Vdet1_0 – 0.1) V	—	250	500	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V		—	1.7	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾			—	—	100	μs

Notes:

1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.11 Voltage Detection 2 Circuit Characteristics
($V_{CC} = 1.8$ to 5.5 V and $T_{opr} = -20$ to 85 °C (N version)/ -40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Vdet2	Voltage detection level Vdet2_0 ⁽¹⁾	At the falling of Vcc		3.70	4.0	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit			—	0.10	—	V
—	Voltage detection 2 circuit response time ⁽²⁾	In operation	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	μs
		In stop mode	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	200	500	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V		—	1.7	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾			—	—	100	μs

Notes:

1. The voltage detection level varies with detection targets. Select the level with the VCA24 bit in the VCA2 register.
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.12 Power-on Reset Circuit Characteristics ⁽¹⁾
($T_{opr} = -20$ to 85 °C (N version)/ -40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
trth	External power Vcc rise gradient		0	—	50000	mV/ms

Note:

1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.

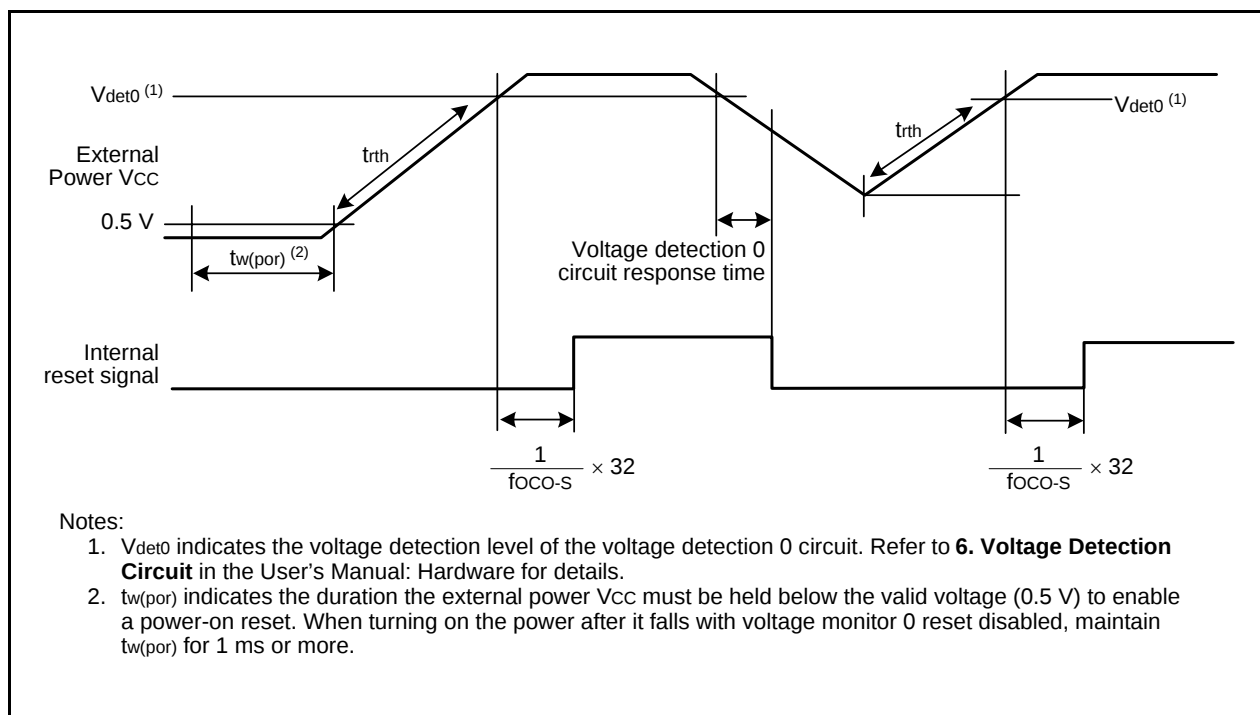


Figure 5.3 Power-on Reset Circuit Characteristics

5.1.4 DC Characteristics

Table 5.18 DC Characteristics (1) [4.0 V ≤ V_{CC} ≤ 5.5 V]
(T_{opr} = −20 to 85 °C (N version)/ −40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter		Condition			Standard			Unit
						Min.	Typ.	Max.	
V _{OH}	Output "H" voltage		Port P8 ⁽¹⁾	V _{CC} = 5V	I _{OH} = −20 mA	V _{CC} − 2.0	−	V _{CC}	V
			Other pins	V _{CC} = 5V	I _{OH} = −5 mA	V _{CC} − 2.0	−	V _{CC}	V
V _{OL}	Output "L" voltage		Port P8 ⁽¹⁾	V _{CC} = 5V	I _{OL} = 20 mA	−	−	2.0	V
			Other pins	V _{CC} = 5V	I _{OL} = 5 mA	−	−	2.0	V
V _{T+} −V _{T−}	Hysteresis	INT0, INT1, INT2, INT3, INT5, INT7, KI0, KI1, KI2, KI3, KI4, KI5, KI6, KI7, TRCIOA, TRCIOB, TRCIOA, TRCIOC, TRCIOD, TRJ0IO, TRJ1IO, TRCTRG, TRCCLK, ADTRG, RXD0, CLK0, SSI, SCL, SDA, SSO				0.05	0.5	−	V
		RESET, WKUP0				0.1	0.8	−	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5 V			−	−	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5 V			−	−	−5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5 V			20	40	80	kΩ
R _{FXIN}	Feedback resistance	XIN				−	2.0	−	MΩ
R _{FXCIN}	Feedback resistance	XCIN				−	14	−	MΩ
V _{RAM}	RAM hold voltage		During stop mode			1.8	−	−	V

Note:

1. This applies when the drive capacity of the output transistor is set to High by P8DRR register. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.19 DC Characteristics (2) [4.0 V ≤ V_{CC} ≤ 5.5 V]
(T_{opr} = −20 to 85 °C (N version)/ −40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter		Condition							Standard			Unit	
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max. (3)		
			XIN (2)	XCIN	High-Speed	Low-Speed								
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	4.7	10	mA	
			16 MHz	Off	Off	125 kHz	No division	—		—	3.9	8	mA	
			10 MHz	Off	Off	125 kHz	No division	—		—	2.3	—	mA	
			20 MHz	Off	Off	Off	No division	FMR27 = 1 MSTCR0 = BEh MSTCR1 = 3Fh	Flash memory off Program operation on RAM Module standby setting enabled	—	3.1	—	mA	
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.8	—	mA	
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA	
		High-speed on-chip oscillator mode	10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.0	—	mA	
			Off	Off	20 MHz	125 kHz	No division	—		—	5.0	11	mA	
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	2.1	—	mA	
		Low-speed on-chip oscillator mode	Off	Off	4 MHz	125 kHz	Divide-by-16	MSTCR0 = BEh MSTCR1 = 3Fh		—	0.9	—	mA	
			Off	Off	Off	125 kHz	No division	FMR27 = 1 VCA20 = 0		—	110	320	μA	
		Low-speed clock mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	63	220	μA	
			Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	60	220	μA	
		Wait mode	Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	46	—	μA	
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	9.0	50	μA	
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	2.8	33	μA	
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	4.6	—	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode		—	2.4	—	μA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25 °C Peripheral clock off	—	0.5	2.2	μA	
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85 °C Peripheral clock off	—	1.2	—	μA	
		Power-off mode	Off	Off	Off	Off	—	—	Power-off 0 Topr = 25 °C	—	0.01	0.1	μA	
			Off	Off	Off	Off	—	—	Power-off 0 Topr = 85 °C	—	0.03	—	μA	
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 25 °C	—	1.8	6.4	μA	
Off	32 kHz		Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 85 °C	—	2.7	—	μA			

Notes:

1. V_{CC} = 4.0 V to 5.5 V, single chip mode, output pins are open, and other pins are V_{SS}.
2. XIN is set to square wave input.
3. V_{CC} = 5.0 V
4. VLCD = V_{CC}, external division resistors are used for VL3 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG26 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.

Table 5.26 Timing Requirements of External Clock Input (XIN, XCIN)
(V_{SS} = 0 V and T_{opr} = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		VCC = 2.2V, Topr = 25°C		VCC = 3V, Topr = 25°C		VCC = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
tC(XIN)	XIN input cycle time	200	—	50	—	50	—	ns
tWH(XIN)	XIN input “H” width	90	—	24	—	24	—	ns
tWL(XIN)	XIN input “L” width	90	—	24	—	24	—	ns
tC(XCIN)	XCIN input cycle time	20	—	20	—	20	—	μs
tWH(XCIN)	XCIN input “H” width	10	—	10	—	10	—	μs
tWL(XCIN)	XCIN input “L” width	10	—	10	—	10	—	μs

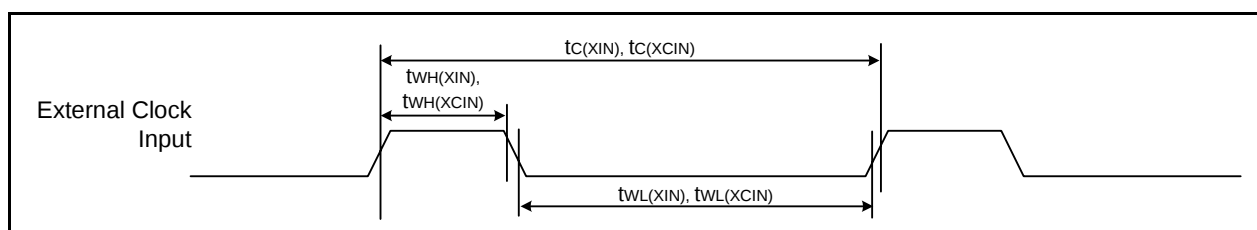


Figure 5.8 External Clock Input Timing

Table 5.27 Timing Requirements of TRJiIO (i = 0 or 1)
(V_{SS} = 0 V and T_{opr} = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
t _c (TRJiO)	TRJiO input cycle time	500	—	300	—	100	—	ns
t _{WH} (TRJiO)	TRJiO input “H” width	200	—	120	—	40	—	ns
t _{WL} (TRJiO)	TRJiO input “L” width	200	—	120	—	40	—	ns

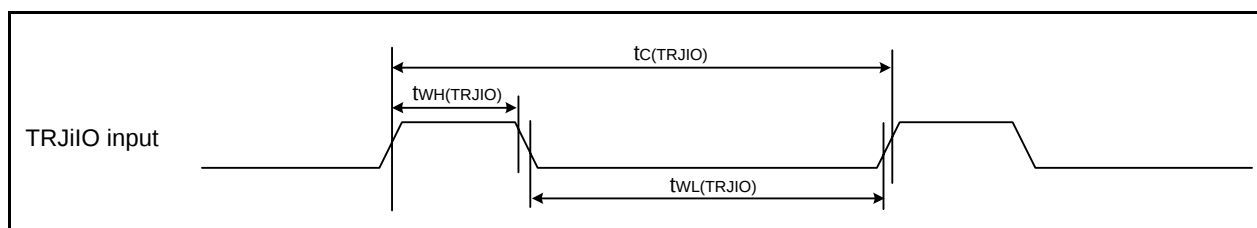


Figure 5.9 Input Timing of TRJiIO

5.2 Electrical Characteristics (R8C/LA6A Group and R8C/LA8A Group)

5.2.1 Absolute Maximum Ratings

Table 5.30 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V _{CC} /AV _{CC}	Supply voltage			–0.3 to 6.5	V
V _I	Input voltage	XIN	XIN-XOUT oscillation on (oscillation buffer ON) ⁽¹⁾	–0.3 to 1.9	V
		XIN	XIN-XOUT oscillation on (oscillation buffer OFF) ⁽¹⁾	–0.3 to V _{CC} + 0.3	V
		P5_4/VL1		–0.3 to VL2 ⁽²⁾	V
		P5_5/VL2		VL1 to VL3	V
		P5_6/VL3		VL2 to 6.5	V
		Other pins		–0.3 to V _{CC} + 0.3	V
V _O	Output voltage	XOUT	XIN-XOUT oscillation on (oscillation buffer ON) ⁽¹⁾	–0.3 to 1.9	V
		XOUT	XIN-XOUT oscillation on (oscillation buffer OFF) ⁽¹⁾	–0.3 to V _{CC} + 0.3	V
		COM0 to COM3		–0.3 to VL3	V
		SEG0 to SEG39		–0.3 to VL3	V
		Other pins		–0.3 to V _{CC} + 0.3	V
P _d	Power dissipation		–40°C ≤ T _{opr} ≤ 85°C	500	mW
T _{opr}	Operating ambient temperature			–20 to 85 (N version)/ –40 to 85 (D version)	°C
T _{stg}	Storage temperature			–65 to 150	°C

Notes:

1. For the register settings for each operation, refer to **7. I/O Ports** and **9. Clock Generation Circuit** in the User's Manual: Hardware.
2. The VL1 voltage should be V_{CC} or below.

Table 5.48 DC Characteristics (2) [4.0 V ≤ V_{CC} ≤ 5.5 V]
(T_{opr} = −20 to 85°C (N version)/ −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition							Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max .	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	4.7	10	mA
			16 MHz	Off	Off	125 kHz	No division	—		—	3.9	8	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	2.3	—	mA
			20 MHz	Off	Off	Off	No division	FMR27 = 1 MSTCR0 = BEh MSTCR1 = 3Fh	Flash memory off Program operation on RAM Module standby setting enabled	—	3.1	—	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.8	—	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.0	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	5.0	11	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	2.1	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTCR0 = BEh MSTCR1 = 3Fh		—	0.9	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	No division	FMR27 = 1 VCA20 = 0		—	110	320	μA
			Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	63	220	μA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	60	220	μA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	46	—	μA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	9.0	50	μA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	2.8	33	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode LCD drive control circuit (4) When external division resistors are used	—	4.6	—	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode	—	2.4	—	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	0.5	2.2	μA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	1.2	—	μA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 0 Topr = 25°C	—	0.01	0.1	μA
		Power-off mode	Off	Off	Off	Off	—	—	Power-off 0 Topr = 85°C	—	0.03	—	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 25°C	—	1.8	6.4	μA
Off	32 kHz		Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 85°C	—	2.7	—	μA		
Off	32 kHz		Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 85°C	—	2.7	—	μA		

Notes:

1. V_{CC} = 4.0 V to 5.5 V, single chip mode, output pins are open, and other pins are V_{SS}.
2. XIN is set to square wave input.
3. V_{CC} = 5.0 V
4. VLCD = V_{CC}, external division resistors are used for VL3 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG39 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.

Table 5.49 DC Characteristics (3) [$2.7\text{ V} \leq V_{CC} < 4.0\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version)/ $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
VOH	Output "H" voltage		Port P7_0, P7_1, P8 (1)	$I_{OH} = -5\text{ mA}$	$V_{CC} - 0.5$	–	V_{CC}
			Other pins	$I_{OH} = -1\text{ mA}$	$V_{CC} - 0.5$	–	V_{CC}
VOL	Output "L" voltage		Port P7_0, P7_1, P8 (1)	$I_{OL} = 5\text{ mA}$	–	–	0.5
			Other pins	$I_{OL} = 1\text{ mA}$	–	–	0.5
VT+·VT-	Hysteresis	INT0, INT1, INT2, INT3, INT4, INT5, INT6, INT7, KI0, KI1, KI2, KI3, KI4, KI5, KI6, KI7, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRJ0IO, TRJ1IO, TRJ2IO, TRCTRG, TRCCLK, ADTRG, RXD0, RXD2, CLK0, CLK2, SSI, SCL, SDA, SSO			0.05	0.4	–
		RESET, WKUP0			0.1	0.8	–
I _{IH}	Input "H" current		$V_I = 3\text{ V}, V_{CC} = 3\text{ V}$		–	–	5.0
I _{IL}	Input "L" current		$V_I = 0\text{ V}, V_{CC} = 3\text{ V}$		–	–	–5.0
R _{PULLUP}	Pull-up resistance		$V_I = 0\text{ V}, V_{CC} = 3\text{ V}$		25	80	140
R _{FXIN}	Feedback resistance	XIN			–	2.0	–
R _{FXCIN}	Feedback resistance	XCIN			–	14	–
V _{RAM}	RAM hold voltage		During stop mode		1.8	–	–

Note:

1. This applies when the drive capacity of the output transistor is set to High by registers P7DDR and P8DDR. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.51 DC Characteristics (5) [$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version)/ $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
VOH	Output “H” voltage		Port P7_0, P7_1, P8 (1)	IOH = −2 mA	Vcc − 0.5	−	Vcc	V
			Other pins	IOH = −1 mA	Vcc − 0.5	−	Vcc	V
VOL	Output “L” voltage		Port P7_0, P7_1, P8 (1)	IOL = 2 mA	−	−	0.5	V
			Other pins	IOL = 1 mA	−	−	0.5	V
VT+-VT-	Hysteresis	INT0, INT1, INT2, INT3, INT4, INT5, INT6, INT7, KI0, KI1, KI2, KI3, KI4, KI5, KI6, KI7, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRJ0IO, TRJ1IO, TRJ2IO, TRCTRG, TRCCLK, ADTRG, RXD0, RXD2, CLK0, CLK2, SSI, SCL, SDA, SSO			0.05	0.4	−	V
		RESET, WKUP0			0.1	0.8	−	V
IIH	Input “H” current		VI = 1.8 V, Vcc = 1.8 V		−	−	4.0	μA
IIL	Input “L” current		VI = 0 V, Vcc = 1.8 V		−	−	−4.0	μA
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 1.8 V		85	220	500	kΩ
RFXIN	Feedback resistance	XIN			−	2.0	−	MΩ
RFXCIN	Feedback resistance	XCIN			−	14	−	MΩ
VRAM	RAM hold voltage		During stop mode		1.8	−	−	V

Note:

1. This applies when the drive capacity of the output transistor is set to High by registers P7DDR and P8DDR. When the drive capacity is set to Low, the value of any other pin applies.

5.2.5 AC Characteristics

Table 5.53 Timing Requirements of Synchronous Serial Communication Unit (SSU)
($V_{CC} = 1.8$ to 5.5 V, $V_{SS} = 0$ V, and $T_{opr} = -20$ to 85°C (N version)/ -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	—	—	tcyc (1)
tHI	SSCK clock "H" width			0.4	—	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	—	0.6	tsucyc
tRISE	SSCK clock rising time	Master		—	—	1	tcyc (1)
		Slave		—	—	1	μs
tFALL	SSCK clock falling time	Master		—	—	1	tcyc (1)
		Slave		—	—	1	μs
tsu	SSO, SSI data input setup time			100	—	—	ns
tH	SSO, SSI data input hold time			1	—	—	tcyc (1)
tLEAD	$\overline{\text{SCS}}$ setup time	Slave		1tcyc + 50	—	—	ns
tLAG	$\overline{\text{SCS}}$ hold time	Slave		1tcyc + 50	—	—	ns
tOD	SSO, SSI data output delay time			—	—	1tcyc + 20	ns
tsA	SSI slave access time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	—	—	1.5tcyc + 100	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	—	—	1.5tcyc + 200	ns
toR	SSI slave out open time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	—	—	1.5tcyc + 100	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	—	—	1.5tcyc + 200	ns

Note:

1. $1\text{tcyc} = 1/f_1(\text{s})$

Table 5.54 Timing Requirements of I²C bus Interface ⁽¹⁾
(V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{cy} + 600 ⁽¹⁾	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{cy} + 300 ⁽¹⁾	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{cy} + 500 ⁽¹⁾	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{cy} ⁽¹⁾	ns
t _{BUF}	SDA input bus-free time		5t _{cy} ⁽¹⁾	–	–	ns
t _{STAH}	Start condition input hold time		3t _{cy} ⁽¹⁾	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{cy} ⁽¹⁾	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{cy} ⁽¹⁾	–	–	ns
t _{SDAS}	Data input setup time		1t _{cy} + 40 ⁽¹⁾	–	–	ns
t _{SDAH}	Data input hold time		10	–	–	ns

Note:

1. 1t_{cy} = 1/f₁(s)

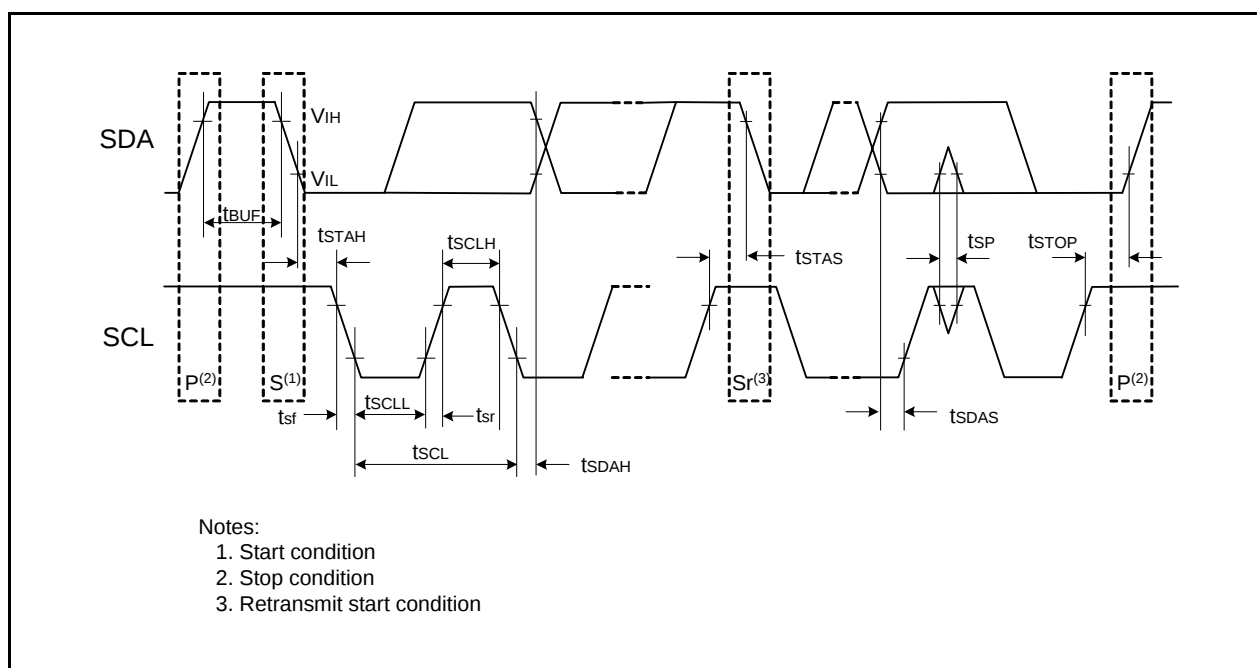


Figure 5.18 I/O Timing of I²C bus Interface

